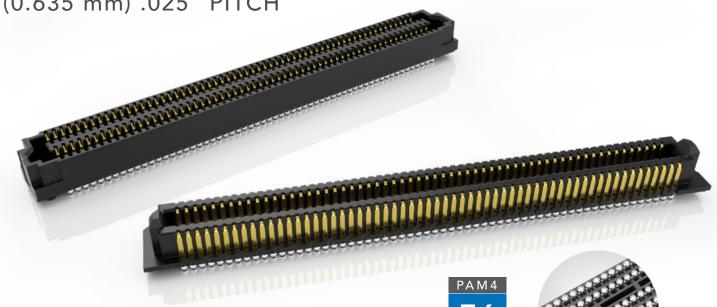
ACCELERATE®HD

HIGH-DENSITY SLIM BODY ARRAYS

(0.635 mm) .025" PITCH



FEATURES & BENEFITS

- Up to 240 positions in 4-row design (400 positions in development)
- · Low-profile 5 mm stack heights
- Slim 5 mm width body design
- Edge Rate® contact system optimized for signal integrity performance
- Open-pin-field for grounding and routing flexibility
- PCIe® 5.0 capable
- Compatible with mPower® (UMPT/UMPS) for a power signal solution

HIGHER DENSITY THAN PREVIOUS GENERATION STRIPS

Solder ball technology for simplified processing

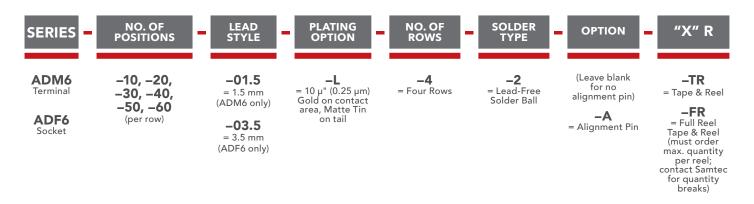
ADM6/ADF6 Series (400 total positions)

KEY SPECIFICATIONS

PITCH	TOTAL POSITIONS	INSULATOR MATERIAL	CONTACT MATERIAL	PLATING	OPERATING TEMP RANGE	CURRENT RATING	WORKING VOLTAGE	LEAD-FREE SOLDERABLE
(0.635 mm) .025"	40 - 240	Black LCP	Copper Alloy	Au or Sn over 50 μ" (1.27 μm) Ni	-55 °C to +125 °C	1.34 A per pin (4 pins powered)	Testing now	Yes



(0.635 mm) .025" PITCH • SLIM BODY OPEN-PIN-FIELD ARRAYS

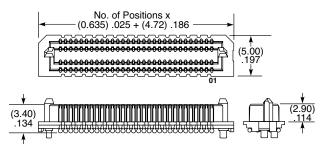


ADM6

Board Mates: ADF6

Standoffs:





View complete specifications at: samtec.com?ADM6

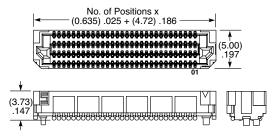
MATED HEIGHTS *				
ADF6	ADM6 LEAD STYLE			
LEAD STYLE	-01.5			
-03.5	(5 mm) .197"			
* Processing conditions will affect mated height.				

ADF6

Board Mates: ADM6

Standoffs:





Notes:

Some sizes, styles and options are non-standard, non-returnable

View complete specifications at: samtec.com?ADF6

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Samtec:

ADF6-60-03.5-L-4-2-A-TR